



**PATENT APPLICATION**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Kazuo TANAKA

Application No.: 09/586,963

Filed: June 5, 2000

For: A SEMICONDUCTOR DEVICE AND A METHOD FOR MAKING THE SAME  
THAT PROVIDE ARRANGEMENT OF A CONNECTING REGION FOR AN  
EXTERNAL CONNECTING TERMINAL (AS AMENDED)

Group Art Unit: 2811

Examiner: C. Nguyen

Docket No.: 039894.01

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**AMENDMENT UNDER 37 C.F.R. §1.111**

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed May 3, 2001, the period for reply being extended by the attached Petition for Extension of Time, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please replace claim 2 as follows:

2. (Twice Amended) A semiconductor device having a multiple wiring layer structure, comprising:

a first conductive layer connected to a conductive member for external connection;

a second conductive layer disposed below said first conductive layer, the second conductive layer having a plurality of openings;

a third conductive layer disposed below said second conductive layer;

a first insulating interlayer disposed between said first conductive layer and said second conductive layer;

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a first through hole provided in said first insulating interlayer;

a fourth conductive layer filling said first through hole, the fourth conductive layer being a material different from that of the first conductive layer;

a second insulating interlayer disposed between said second conductive layer and said third conductive layer;

a second through hole provided in said second insulating interlayer; and

a fifth conductive layer filling said second through hole, the fifth conductive layer being a material different from that of the second conductive layer, wherein said first insulating interlayer and said second insulating interlayer are connected to each other through said openings of said second conductive layer, and a contiguous section of said first insulating interlayer with said second insulating interlayer is, thereby, formed between said first conductive layer and said third conductive layer.

#### REMARKS

Claims 2-8, 12-14 and 21 are pending. Claims 4, 5, 7-11, 13, 14 and 21 have previously been withdrawn from consideration and claims 1, 9-11 and 15-20 are canceled.

Reconsideration based on the following remarks is respectfully requested.

I. CLAIMS 2, 3, 6 AND 12 DEFINE ALLOWABLE SUBJECT MATTER

A. §102(e) Rejection

Item 5 of the Office Action rejects claims 2, 3 and 6 under 35 U.S.C. §102(e) as being anticipated by U.S. Patent No. 5,751,065 to Chittipeddi et al. (hereinafter "Chittipeddi"). The rejection is respectfully traversed.

Contrary to the Office Action, Chittipeddi does not disclose a specific claimed feature of the present invention. Namely, Chittipeddi does not disclose a fourth conductive layer filling the first through hole in the first insulating layer and having a material different from that of the first conductive layer and a fifth conductive layer filling a second through hole, the